



Dual-band Wi-Fi 6 plus Bluetooth® Combo SDIO Modules

SX-SDMAX





Low Power Wireless LAN Module Powered by NXP's IW611

Overview

The SX-SDMAX is a Wi-Fi 6 (IEEE 802.11a/b/g/n/ac/ax) plus Bluetooth® v5.3 that supports SDIO as its host interface. Powered by NXP's highly integrated IW611 chipset, the Wi-Fi 6 module delivers higher throughput, better network efficiency, lower latency, and improved range over previous-generation Wi-Fi standards. The module supports SDIO as its host interface, which is a popular choice for many battery-operated device applications, as it provides the perfect balance between performance and power consumption. In addition, by supporting a wide temperature range, it is a wireless LAN module that is ideal for wireless compatibility with a wide range of products, from industrial equipment to small devices.

Efficient, Faster, & Lower Latency with Wi-Fi 6

The latest Wi-Fi 6 technology introduces features such as OFDMA, 1024QAM, and Target Wake Time (TWT) bringing higher throughput, better network efficiency, lower latency, and improved range over previous-generation Wi-Fi standards.

The SX-SDMAX with its SDIO host interface combines all the benefits of Wi-Fi 6 while optimizing power consumption to deliver unmatched Wi-Fi performance with improved battery life, making it an ideal solution for many battery-operated embedded devices.

Wi-Fi 6 Features

1) Efficiency MU-MIMO OFDMA Improved efficiency and stability in dense networks. Wi-Fi 6 delivers data reliably with low latency even in congested radio wave environments.

(2) Power Saving TWT Multiple BSS

Wi-Fi 6 has introduced new features like Target Wake Time which allows devices to negotiate when and how frequently they will wake up to send or receive data. This Wi-Fi 6/6E feature increases device sleep time and greatly improves battery life. It also incorporates a mechanism for avoiding collisions between packets and for efficiently avoiding radio wave interference for efficient communication.

SX-SDMAX Features

- PHY data rate up to 600Mbps (at 5GHz/80MHz/MSC11)
- Single stream, 1x1
- Powered by NXP's IW611 chipset
- Host interface: Wireless LAN SDIO3.0 compatible, Bluetooth[®] UART
- 80MHz band mode (5GHz)
- High density modulation mode (1024 QAM)
- Bluetooth[®] v5.3 Class1 compatible
- RoHS compliant
- Modular certifications(Planned) : Japan, USA, Canada, Europe, UK

Applications

Ideal for many battery operated medical devices, mobile printers, Hand held POS and terminals, barcode scanners, IoT Applications etc.

Specifications

Product Name	SX-SDMAX-2530S SX-SDMAX-2530C SX-SDMAX-M2				
Chipset	NXP IW611				
Host Interface	WLAN : SDIO3.0 Bluetooth® : UART				
Wi-Fi Standard	IEEE 802.11a/b/g/n/ac/ax (1x1)				
Bluetooth®	Bluetooth® v5.3(BR/EDR/LE Compliant)				
Antenna Connector	MHF Connector :1				
Operating Voltage	Main Power Supply : 3.3V + 1.8V IO Power Supply:1.8V or 3.3V				
Current Consumption (Peak Value)	Voltage	VDD18		VDD33	
		Tx	Rx	Tx	Rx
	Wi-Fi:2.4GHz	190mA	130mA	200mA	10mA
	Wi-Fi:5GHz	260mA	150mA	240mA	10mA
	Bluetooth®	150mA	80mA	20mA	10mA
Operating Environment	Temperature : -40 \sim 85°C Humidity : 95% RH or less (Without Condensation)				
Size	SX-SDMAX-25305:17.0 × 18.0 × 2.65mm SX-SDMAX-2530C:24.0 × 24.0 × 4.45mm SX-SDMAX-M2 :17.0 × 18.0 × 2.65mm				
Package Type	SMT: 44-pins Land Grid Array (Direct Solder) B2B: 40 pins board to board connector M.2 Card: M.2 Card type 2230-S3-E				

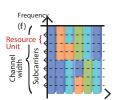
Product Lineup



Long Term Supply Guarantee

To meet the needs of the medical and industrial fields, where product lifespans of 10 years or more are required, the following initiatives have been implemented for this product.

- Uses chipset covered by the NXP Long-Term Supply Program (15 years)
- In-House manufacturing and storage to provide flexibility to build and deliver pars when you need them.

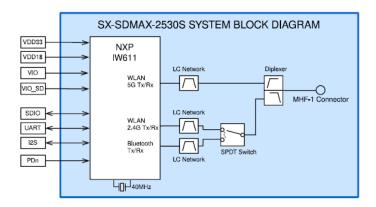


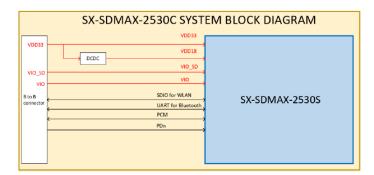


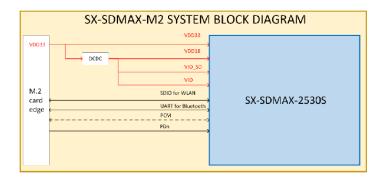
Time(t)

SX-SDMAX

Block Diagram







Wireless Driver *1

[WLAN]

Linux

- Station, Access Point Mode
- WPA[™]/WPA2[™]/WPA3[™] Authentication
- IEEE 802.1X(TLS, TTLS, PEAP, LEAP, FAST)
- WPS2.0 Support*2
- Wi-Fi Direct[®] Support^{*2}

[Bluetooth®]

 In order to support the Bluetooth[®] v5.3 standard, it is necessary to combine a stack and profile that support the Bluetooth[®] v5.3 standard.

Please contact our sales representative for compatible Bluetooth[®] stacks and profiles.

*1 : Please contact our sales representative for details of compatible drivers.

*2 When using, it is necessary to obtain Wi-Fi Alliance certification separately.

Evaluation

Although the NXP i.MX BSP will already include Wi-Fi drivers for SX-SDMAX to enable plug-n-play evaluation, Silex also provides a separate evaluation Linux OS image which not only includes Silex's optimized driver but also board data files, and other Linux test tools ideal for evaluation.

What you will need?

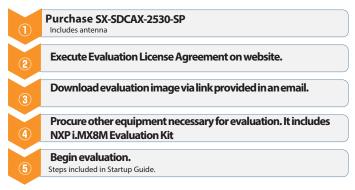
- · SX-SDCAX-2530
- NXP i.MX8M Evaluation Kit (MCIMX8M-EVKB)



Other useful tools inluded in Silex image :

- \cdot Wireless LAN management command iw
- · Throughput test iperf
- · Station/AP function hostapd, wpa_supplicant
- ·DHCP udhcpd、udhcpc

To get started:





https://www.silextechnology.com/connectivity-solutions/embedded-wireless/sx-sdmax



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Specifications are subject to change without notice for improvement. The listed specifications are as of March 2023.



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